L Number	Hits	Search Text	DB	Time stamp
1	0		USPAT;	2004/09/13 16:56
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_			IBM_TDB	0004/00/12 16 56
3	280	(ceramic adj substrate) with molten	USPAT; US-PGPUB;	2004/09/13 16:56
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
4	1	(ceramic adj substrate) with molten with	USPĀT;	2004/09/13 17:36
		(base adj metal)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
-	47		IBM_TDB	0004/00/12 17:00
5	47	(ceramic adj substrate) with (molten adj metal)	USPAT; US-PGPUB;	2004/09/13 17:28
		Metal/	EPO; JPO;	
			DERWENT;	
			IBM TDB	
6	90	(ceramic adj substrate) same (molten adj	USPĀT;	2004/09/13 17:26
		metal)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
7	7	(ceramic adj substrate) same (melted adj	IBM_TDB USPAT;	2004/09/13 17:26
'	<b>'</b>	metal)	US-PGPUB;	2004/03/13 17.20
		1100027	EPO; JPO;	
			DERWENT;	·
			IBM_TDB	
8	51	(ceramic adj plate) with (molten adj	USPAT;	2004/09/13 17:28
		metal)	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
9	0	(ceramic adj plate) with molten with (base	USPAT;	2004/09/13 17:37
		adj metal)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
10	0	(ceramic adj plate) same molten same (base	IBM_TDB USPAT;	2004/09/13 17:39
1 10		adj metal)	US-PGPUB;	2004/03/13 17.33
		,,	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
11	0	(upper adj circuit adj plate) same molten	USPAT;	2004/09/13 17:40
		same (base adj metal)	US-PGPUB; EPO; JPO;	
]			DERWENT;	
			IBM TDB	
12	0	(upper adj circuit adj plate) same (base	USPĀT;	2004/09/13 17:40
		adj metal)	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
13	0	upper adj circuit adj plate) and (base	USPAT;	2004/09/13 17:40
		adj metal)	US-PGPUB;	= = = = = = = = = = = = = = = = = = =
			EPO; JPO;	
]			DERWENT;	
14	3	(upper add discust add master and (master	IBM_TDB	2004/00/12 17:41
**	3	(upper adj circuit adj plate) and (molten adj metal)	USPAT; US-PGPUB;	2004/09/13 17:41
		and meeting	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
15	408	(upper adj plate) and (molten adj metal)	USPĀT;	2004/09/13 17:47
]			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
		<u> </u>	10.1_100	

	т			
16	141	(upper adj plate) same (molten adj metal)	USPAT;	2004/09/13 17:41
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
17	3	(upper adj plate) same (molten adj	USPAT;	2004/09/13 17:42
		metal) same ceramic	US-PGPUB;	2004/03/13 17:42
			EPO; JPO;	
			DERWENT;	1
			IBM TDB	}
18	3	(upper adj plate) same (molten adj metal)	USPĀT;	2004/09/13 17:42
		same ceramic	US-PGPUB;	
			EPO; JPO;	
		·	DERWENT;	
	100		IBM_TDB	
19	101	(upper adj plate) and (molten adj metal)	USPAT;	2004/09/13 17:42
1		and ceramic	US-PGPUB;	
İ			EPO; JPO;	
	1		DERWENT;	
20	1	(upper add plate) and (malter add matel)	IBM_TDB	2004/00/12 10-20
20		(upper adj plate) and (molten adj metal) and (power adj module)	USPAT; US-PGPUB;	2004/09/13 18:30
		and (power ad) module/	EPO; JPO;	
	1		DERWENT;	
	1		IBM TDB	
21	27	257/150.ccls.	USPAT;	2004/09/13 18:31
			US-PGPUB;	10.51
			EPO; JPO;	ļ
			DERWENT;	
			IBM TDB	1
22	160	257/177.ccls.	USPAT;	2004/09/13 18:31
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
122	20	057/1001-	IBM_TDB	
23	30	257/180.ccls.	USPAT;	2004/09/13 18:31
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
24	53	257/182.ccls.	USPAT;	2004/09/13 18:32
			US-PGPUB;	2001,03,13 10.32
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
25	1564	257/686.ccls.	USPAT;	2004/09/13 18:33
			US-PGPUB;	
			EPO; JPO;	[
			DERWENT;	
26	500	257/6041-	IBM_TDB	0004/00/10
40	528	257/684.ccls.	USPAT;	2004/09/13 18:34
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
27	488	257/685.ccls.	USPAT;	2004/09/13 18:34
- '	100	23., 333.6613.	US-PGPUB;	2004/03/13 18:34
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
28	702	257/687.ccls.	USPAT;	2004/09/13 18:35
			US-PGPUB;	,
			EPO; JPO;	
			DERWENT;	
		1	IBM_TDB	
29	672	257/703.ccls.	USPAT;	2004/09/13 18:38
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	L		IBM_TDB	

30	1 402	057/705 0-10	HCDAM.	2004/00/12 10:40
30	483	257/705.ccls.	USPAT; US-PGPUB;	2004/09/13 18:40
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
31	1167	257/706.ccls.	USPAT;	2004/09/13 18:42
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
32	2185	257/712.ccls.	USPAT;	2004/09/13 18:44
			US-PGPUB;	
	1		EPO; JPO; DERWENT;	
			IBM TDB	
33	1141	257/713.ccls.	USPAT;	2004/09/13 18:47
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
34	960	257/717.ccls.	USPĀT;	2004/09/13 18:48
			US-PGPUB;	
1			EPO; JPO;	
*			DERWENT;	
25	2005	057/750 1-	IBM_TDB	0004/00/10 10 50
35	2865	257/758.ccls.	USPAT;	2004/09/13 18:53
			US-PGPUB; EPO; JPO;	
1			DERWENT;	
			IBM TDB	
36	1159	257/750.ccls.	USPAT;	2004/09/13 18:57
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
37	940	257/762.ccls.	USPAT;	2004/09/13 18:58
			US-PGPUB;	
	į		EPO; JPO;	
			DERWENT;	
38	419	257/765.ccls.	IBM_TDB USPAT;	2004/09/13 18:59
30	419	2377703.0015.	US-PGPUB;	2004/09/13 18:39
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
39	418	257/772.ccls.	USPĀT;	2004/09/13 19:00
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	0004/00/20 == ==
-	33		USPAT;	2004/09/10 11:13
		(heat adj sink) and (ceramic adj substrate)	US-PGPUB;	
		Subsciate;	EPO; JPO; DERWENT;	
			IBM TDB	
_	4	   (power adj semiconductor adj module) and	USPAT;	2004/09/08 14:44
		(casting adj method)	US-PGPUB;	,,,
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	13		USPAT;	2004/09/08 15:17
		and (ceramic adj substrate)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	20	   (chip) and (circuit adj plate) and (heat	IBM_TDB USPAT;	2004/09/08 15:17
	20	(chip) and (circuit adj plate) and (neat   adj sink) and (ceramic adj substrate)	US-PGPUB;	2004/03/00 13:1/
		adj blik, and (ceramic adj subscrace)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
L		·	·	<del>                                     </del>

_	0	(power adj semiconductor adj module) and (integrally adj formed adj terminals)	USPAT; US-PGPUB; EPO; JPO;	2004/09/08 17:05
			DERWENT; IBM_TDB	
-	1	(power adj semiconductor adj module) and (integral adj terminals)	USPAT; US-PGPUB; EPO; JPO;	2004/09/08 17:07
			DERWENT; IBM TDB	
-	8	(outer adj case) and (integral adj terminals)	USPAT; US-PGPUB; EPO; JPO;	2004/09/08 17:07
			DERWENT; IBM_TDB	
-	24	no adj lower adj plate	USPAT; US-PGPUB; EPO; JPO;	2004/09/10 11:16
			DERWENT; IBM_TDB	
_	52	(circuit adj plate) and (power adj module)	USPAT; US-PGPUB; EPO; JPO;	2004/09/10 11:58
_	7	(circuit adj plate) and (casting adj	DERWENT; IBM_TDB USPAT;	2004/09/10 11:40
	,	method)	US-PGPUB; EPO; JPO;	2004/03/10 11.40
_	5	(circuit adj plate) and (packaging adj	DERWENT; IBM_TDB USPAT;	2004/09/10 11:40
		method)	US-PGPUB; EPO; JPO; DERWENT;	
_	43	power adj module adj package	IBM_TDB USPAT;	2004/09/10 12:22
			US-PGPUB; EPO; JPO; DERWENT;	
-	591	(power adj module) with case	IBM_TDB USPAT; US-PGPUB;	2004/09/10 12:23
			EPO; JPO; DERWENT;	
_	19	(power adj module) with case with ceramic	IBM_TDB USPAT; US-PGPUB;	2004/09/10 12:23
			EPO; JPO; DERWENT; IBM TDB	
-	11	solder adj material adj removed	USPAT; US-PGPUB;	2004/09/13 12:32
			EPO; JPO; DERWENT; IBM_TDB	
_	17	solder adj layer adj removed	USPAT; US-PGPUB; EPO; JPO;	2004/09/13 11:41
_	22	no adj solder adj layer	DERWENT; IBM_TDB USPAT;	2004/09/13 11:56
	22	and doubted any layer	US-PGPUB; EPO; JPO;	2001/05/15 11.50
_	0	no adj solder adj film	DERWENT; IBM_TDB USPAT;	2004/09/13 12:31
			US-PGPUB; EPO; JPO; DERWENT;	
			IBM_TDB	

	1	l no add goldon add rogion	USPAT;	2004/09/13 12:05
-	1	no adj solder adj region	US-PGPUB:	2004/09/13 12:03
	1		,	
			EPO; JPO;	
			DERWENT;	
		l	IBM_TDB	,
1-	120	' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' '	USPAT;	2004/09/13 12:10
		substrate)	US-PGPUB;	
1			EPO; JPO;	
1			DERWENT;	
			IBM_TDB	
-	24	((metal adj base) with (ceramic adj	USPAT;	2004/09/13 14:25
1		substrate)) and (power adj module)	US-PGPUB;	
		_	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	3	no adj solder adj join	USPAT;	2004/09/13 12:31
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	4	solder adj material adj omitted	USPAT;	2004/09/13 12:32
		,	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	3	solder adj layer adj omitted	USPAT;	2004/09/13 12:32
			US-PGPUB;	=== 3, ==, == =====
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	3	(base adj integral adj type) and (power	USPAT;	2004/09/13 16:55
		adj module)	US-PGPUB;	= = = = = = = = = = = = = = = = =
	1	445 11044207	EPO; JPO;	
			DERWENT;	
			IBM TDB	